

TMG10N10S

N-Channel Enhancement Mosfet

General Description	General Features
<ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant 	$V_{DS} = 100V$ $I_D = 10A$ $R_{DS(ON)} = 16\text{ m}\Omega$ (typ.) @ $V_{GS} = 10V$
Applications	100% UIS Tested 100% R_g Tested



S:SOP-8L			
PIN1	PIN1	S	G
Marking: G10N10			

Absolute Maximum Ratings ($T_A = 25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	10	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	0.7	A
I_{DM}	Pulsed Drain Current ²	37	A
EAS	Single Pulse Avalanche Energy ³	57	mJ
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	80	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	25	$^\circ C/W$

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 Electrical Characteristics: ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250 \mu A$	100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=100V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$	---	---	± 100	nA
On Characteristics						
V_{GS(th)}	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250 \mu A$	1.0	2.0	3.0	V
R_{DS(on)}	Drain-Source On Resistance	$V_{GS}=10V, I_D=10A$	---	16	19	$m\Omega$
		$V_{GS}=4.5V, I_D=7A$	---	---	---	$m\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=100kHz$	---	1004	---	pF
C_{oss}	Output Capacitance		---	185	--	
C_{rss}	Reverse Transfer Capacitance		---	9.8	---	
Switching Characteristics						
t_{d(on)}	Turn-On Delay Time	$V_{DS}=50V, I_D=5A, R_{ENG}=10 \Omega, V_{GS}=10V$	---	16.6	---	ns
t_r	Rise Time		---	3.8	---	ns
t_{d(off)}	Turn-Off Delay Time		---	75.5	---	ns
t_f	Fall Time		---	46	---	ns
Q_g	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V, I_D=5A$	---	16.2	---	nc
Q_{gs}	Gate-Source Charge		---	2.8	---	nc
Q_{gd}	Gate-Drain "Miller" Charge		---	4.1	---	nc
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=12A$	---	---	1.3	V
I_s	Continuous Drain Current	$V_D=V_G=0V$	---	---	10	A
I_{SM}	Pulsed Drain Current		---	---	37	A
T_{rr}	Reverse Recovery Time	$I_S=5A, T_J=25^\circ C$	---	49	---	ns
Q_{rr}	Reverse Recovery Charge		---	61.8	---	nc

Notes:

- Calculated continuous current based on maximum allowable junction temperature.
- Repetitive rating; pulse width limited by max. junction temperature.
- Pd is based on max. junction temperature, using junction-case thermal resistance.
- The value of R_{eJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^\circ C$.
- $V_{DD}=50 V, V_{GS}=10 V, L=0.3 mH, \text{ starting } T_J=25^\circ C$

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Typical Characteristics

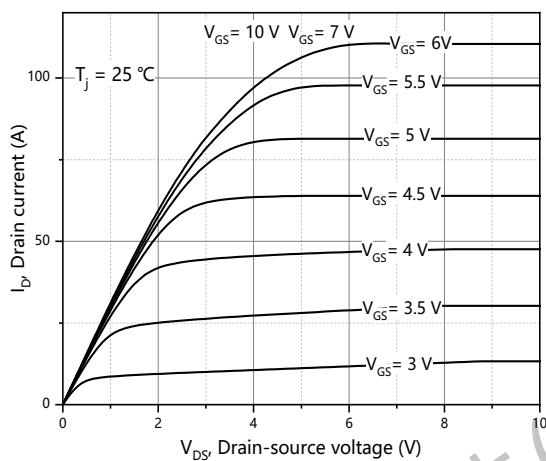


Figure 1. Typ. output characteristics

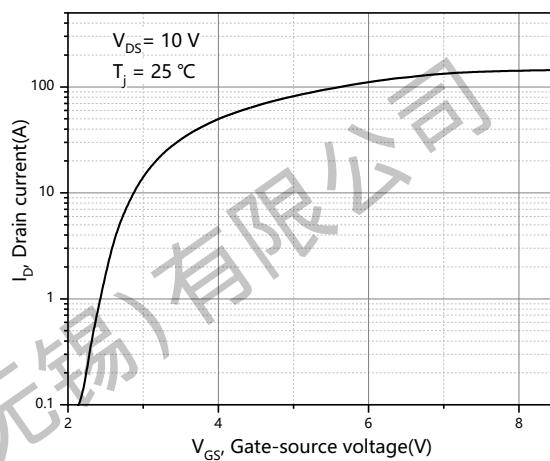


Figure 2. Typ. transfer characteristics

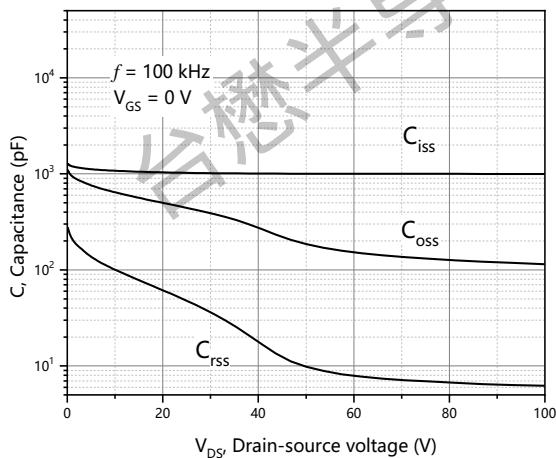


Figure 3. Typ. capacitances

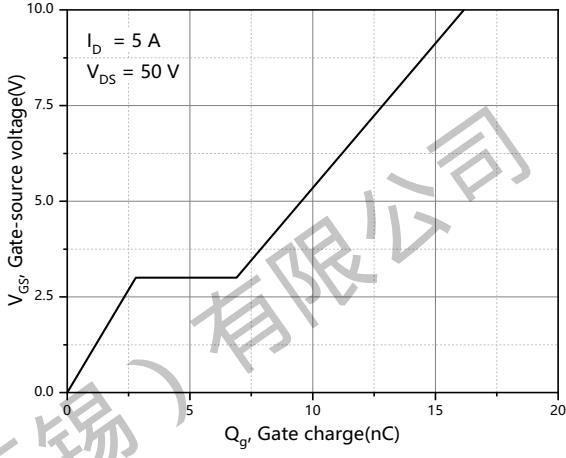


Figure 4. Typ. gate charge

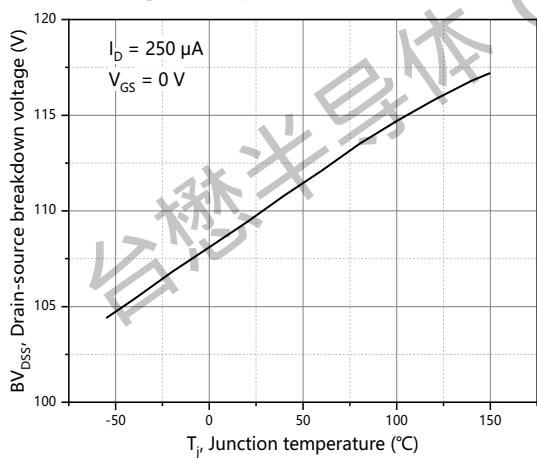


Figure 5. Drain-source breakdown voltage

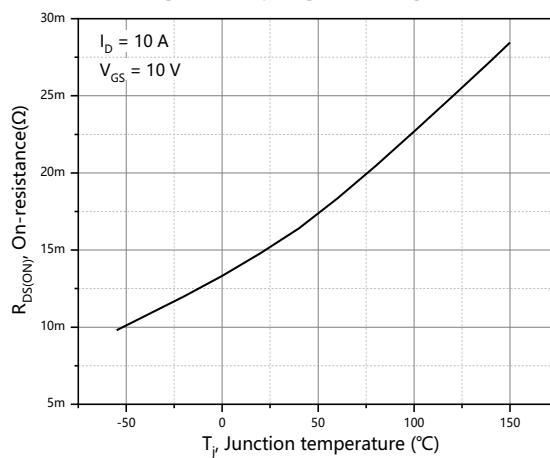


Figure 6. Drain-source on-state resistance

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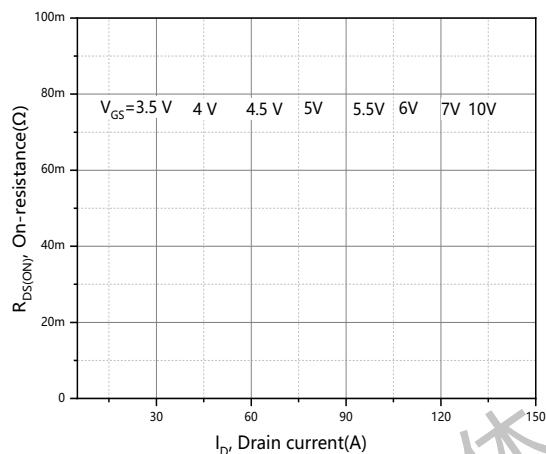


Figure 7. Drain-source on-state resistance

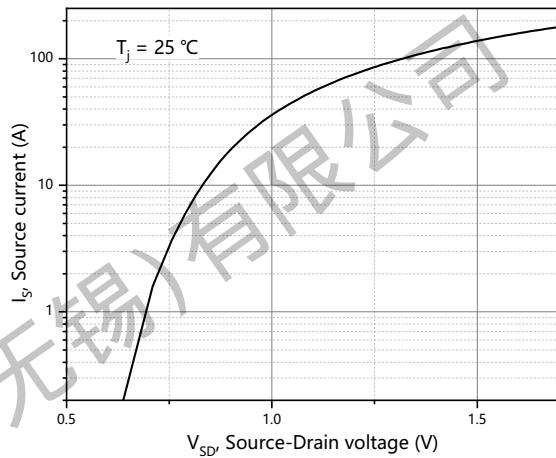


Figure 8. Forward characteristic of body diode

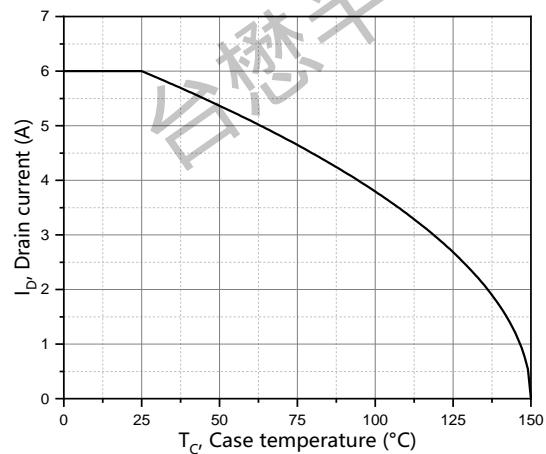


Figure 9. Drain current

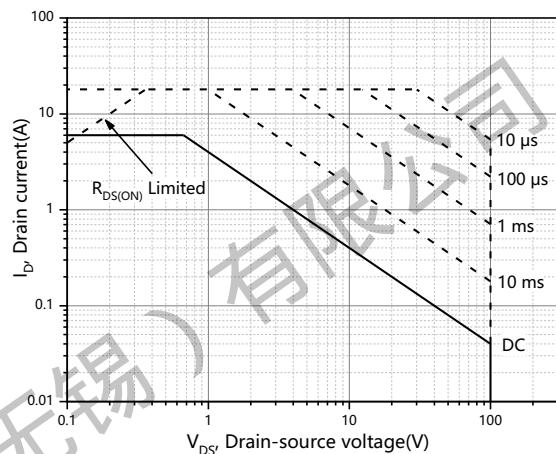
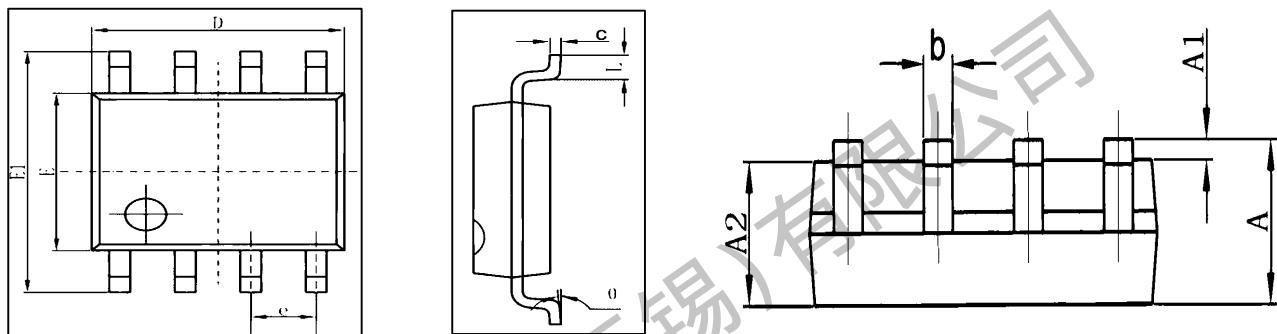


Figure 10. Safe operation area for $T_c=25^\circ\text{C}$

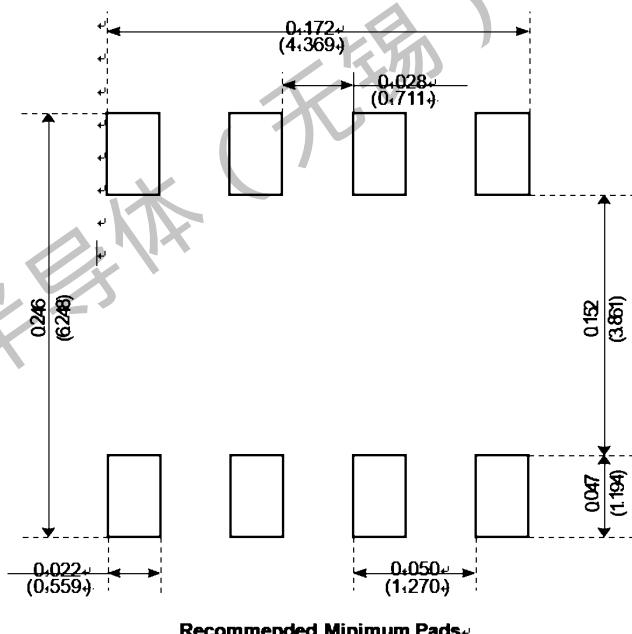
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Package Mechanical Data:SOP-8L



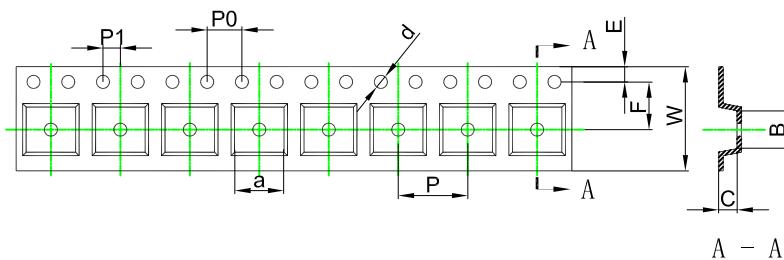
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



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SOP-8L Embossed Carrier Tape

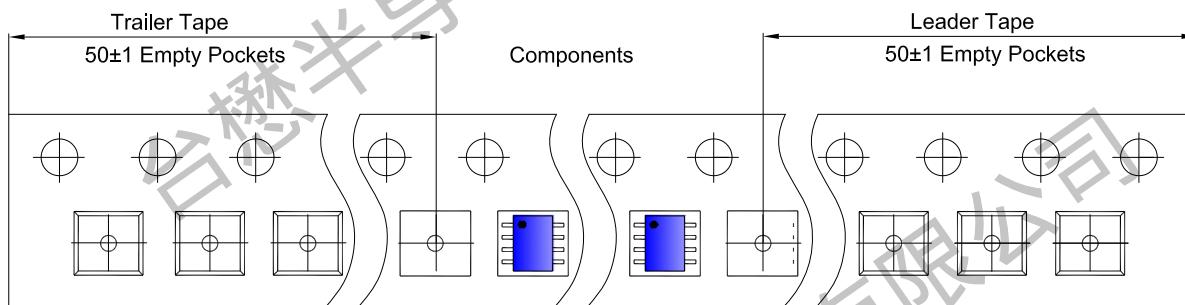


Packaging Description:

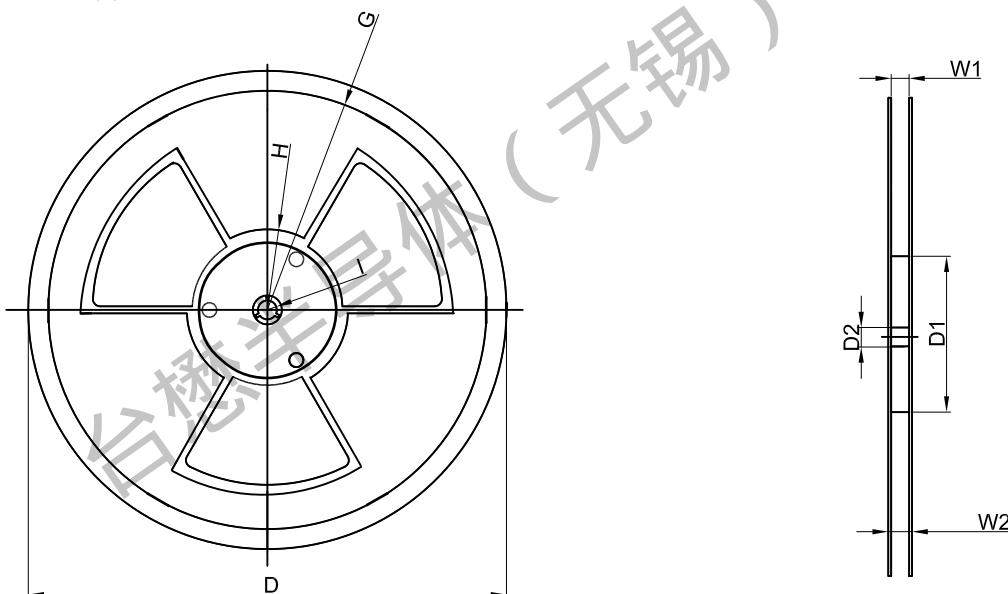
SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
SOP-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

SOP-8L Tape Leader and Trailer



SOP-8L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13" Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3,000 pcs	13 inch	6,000 pcs	370×355×52	48,000 pcs	400×360×368	

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Revision history:

Date	Rev	Description	Page
2023.07.22	23.07	Original	